L Number	Hits	Search Text	DB	Time stamp
1	6629	((copper or cu) near3 (layer or film or panel or coating)) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/20 16:47
2	4694	(((copper or cu) near3 (layer or film or panel or coating)) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5)) and ((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20
3	1533	((((copper or cu) near3 (layer or film or panel or coating)) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5)) and ((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5))) and (circuit adj board\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 16:50
4	1020	(((((copper or cu) near3 (layer or film or panel or coating)) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5)) and ((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5))) and (circuit adj board\$3)) and (mask\$5 or resist or photomask\$5 or photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:06
	161	<pre>((((((copper or cu) near3 (layer or film or panel or coating)) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5)) and ((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5))) and (circuit adj board\$3)) and (mask\$5 or resist or photomask\$5 or photoresist)) and ((layer or film or coating or panel) near5 (cathode or electrode))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:05
6	19698	<pre>((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (laser or drill\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/20 17:03
7	1118	<pre>(((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (laser or drill\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5))) and (circuit adj board\$3)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 16:59
8	7	<pre>(((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (laser or drill\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5))) and (circuit adj board\$3)) and ((layer or film or coating or panel) near5 (cathode or electrode))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20
9	993673	<pre>(dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/20 17:04

7	

			*	
10	73388	((dielectric or base or core or board or	USPAT;	2003/08/20
		insulat\$5 or non\$2conduct\$5 or epoxy or	US-PGPUB;	17:04
		polymer\$3 or resin\$5 or body) near5	EPO; JPO;	·
		(via\$3 or hole\$3 or trench\$3 or opening\$3	DERWENT;	
		or cavit\$5)) and (circuit adj board\$3)	IBM TDB	
11	19413	(((dielectric or base or core or board or	USPAT;	2003/08/20
	l	insulat\$5 or non\$2conduct\$5 or epoxy or	US-PGPUB;	17:05
		polymer\$3 or resin\$5 or body) near5	EPO; JPO;	
,		(via\$3 or hole\$3 or trench\$3 or opening\$3	DERWENT;	
ļ:		or cavit\$5)) and (circuit adj board\$3))	IBM TDB	
		and copper	_	
12	1924	(((dielectric or base or core or board	USPAT;	2003/08/20
		or insulat\$5 or non\$2conduct\$5 or epoxy	US-PGPUB;	17:05
		or polymer\$3 or resin\$5 or body) near5	EPO; JPO;	
		(via\$3 or hole\$3 or trench\$3 or opening\$3	DERWENT;	
		or cavit\$5)) and (circuit adj board\$3))	IBM TDB	
		and copper) and ((layer or film or		
		coating or panel) near5 (cathode or		
		electrode))		İ
13	1229	((((dielectric or base or core or board	USPAT;	2003/08/20
	•	or insulat\$5 or non\$2conduct\$5 or epoxy	US-PGPUB;	17:06
		or polymer\$3 or resin\$5 or body) near5	EPO; JPO;	
		(via\$3 or hole\$3 or trench\$3 or opening\$3	DERWENT;	
		or cavit\$5)) and (circuit adj board\$3))	IBM TDB	
		and copper) and ((layer or film or	- · · · -	
		coating or panel) near5 (cathode or		
		electrode))) and (mask\$5 or resist or		
		photomask\$5 or photoresist)		ļ
15	93	(((((dielectric or base or core or board	USPAT;	2003/08/20
		or insulat\$5 or non\$2conduct\$5 or epoxy	US-PGPUB;	17:07
		or polymer\$3 or resin\$5 or body) near5	EPO; JPO;	
		(via\$3 or hole\$3 or trench\$3 or opening\$3	DERWENT;	
		or cavit\$5)) and (circuit adj board\$3))	IBM TDB	
		and copper) and ((layer or film or	_	
		coating or panel) near5 (cathode or		1
		electrode))) and (mask\$5 or resist or		
· ·		photomask\$5 or photoresist)) and blind		
14	121	((((dielectric or base or core or board	USPAT;	2003/08/20
		or insulat\$5 or non\$2conduct\$5 or epoxy	US-PGPUB;	17:07
		or polymer\$3 or resin\$5 or body) near5	EPO; JPO;	
		(via\$3 or hole\$3 or trench\$3 or opening\$3	DERWENT;	· ·
		or cavit\$5)) and (circuit adj board\$3))	IBM_TDB	
		and copper) and ((layer or film or	_	1
		coating or panel) near5 (cathode or		
		electrode))) and blind		
		coating or panel) near5 (cathode or		